



# Preparing Templated Silicon Surfaces for III-V Epitaxy

By: Didiel Vazquez-Morales

Major: Chemical Engineer

Oxnard College and Ventura College

Mentor: Daniel Pennachio

Faculty advisor: Dr. Palmstrøm





### <u>Reducing waste energy</u> <u>during data transfer</u> <u>using photonics</u>

- Electrical wires produce heat
- Silicon is cheap and used in electronic devices
- Big problem: Silicon is an inefficient light emitter
- III-V materials used in lasers to emit light
- Solution: III-V material on Si





http://tech.blorge.com/wp-content/uploads/2014/04/Samsung-Galaxy-54-vs-iPhone-5.iog



https://www.semiwiki.com/forum/attachments/content/attachments/ 11601d1405647406-300mm-450mm-wafer-comparison-jpg

http://www.plyojump.com/classes/images/hardware/transistor\_pcb.jpg



http://www.visiblediodelasers.com/wpcontent/uploads/laserdiode11.jpg





III-V: Zinc blende crystal structure

# Clean interface avoids defects on III-V

#### <u>crystals</u>

- Grow III-V material on top of the silicon
- Impurities on the silicon surface
- Selectively clean the wafer to remove the native oxide
- Growth III-V epitaxy on selected areas









**III-V:** Zinc blende crystal structure

# Clean interface avoids defects on III-V

#### <u>crystals</u>

- Grow III-V material on top of the silicon
- Impurities on the silicon surface
- Selectively clean the wafer to remove the native oxide
- Growth III-V epitaxy on selected areas





















Anneal: 1200°C 5 minutes

\* Acid Solvent

# ✤acid

10









- Anneal roughened the surface
- Silicon carbide (SiC) formed by incomplete carbon removal.







#### **Future plans:**

- Find the correct time and temperature for anneal to avoid surface roughening
- Cleaning substrates with ozone before outgassing to remove carbon
- Repeat ozone ad remove oxide multiple times to completely remove carbon



## Acknowledgements:







